

# WST Chip /OE Product

*Sep. 2024*





# WaveSplitter History & Key Milestones

- 1996** Company Founded & Established in San Jose, CA .
- Pre 2003** Passive Fiber Optics Components, Focused on WDM / DWDM WavePump and AWG Products.
- 2003-10** Relocated Company to Taiwan in 2005. Started Active Optical TRx Development: 10G LX4 and 100Base-MTRJ to Cisco, and Fiber Optic of HDMI Link TRx.
- 2010-13** Active Optical TRx Products Approved and Received Vendor Code from Google, Amazon, and HP
- 2014-19** 10G and 40G MM TRx Products Approved and Received Vendor Code from Microsoft. Developed 40G SM and 100G MM&SM QSFP TRx & AOCs with Suppliers .
- 2020-21** Established TRx Module Mfg. Factory in Taipei.  
Established LDs Mfg. Factory in Taoyuan & Developed 10/25G CWDM DFB LDs.
- 2021-22** Developed 10/25G LR/BIDI and 25G ER/BIDI TRx Products.  
Developed 25G 1310nm TE/TM Mode DFB LDs for 5G Network & 10G PON Applications.  
Developed 1310nm High Power CW LDs for Si-Photonic Technology Products.
- 2022-23** Developed/Design-in 10G XGSPON BOSA & Combo Q-OSA products for customers  
Developed 40/100G CWDM4 TRx products
- 2023-24** Developing 28G 1310nm TM Mode DFB LDs & BOSA for 25G PON Applications.  
Will Develop 4/8-wavelengths High Power CW LDs for Si-Photonic Technology Products.  
Developing 100G DR1, 400G DR4, 800G 2xDR4/2xFR4 & 1.6T CPO Engine & TRx for HPC/AI/DC.  
Co- Developing 10G/25G MAC PON SFP TRx with customers.



# WaveSplitter Global Offices



- **HQ & Module Factory: Taipei, Taiwan**  
LDs & Module Sales Marketing  
Module R&D  
Module Supply Chain Management  
Qualification and Manufacturing
- **TWN: LDs Factory, Taoyuan, Taiwan**  
LDs & OSA Package Sales Marketing  
LDs & OSA Package R&D  
LDs & OSA Supply Chain Management  
Qualification and Manufacturing
- **N. America: Fremont, CA**  
Sales Marketing  
Customer Service
- **Japan: Tokyo, Japan**  
Sales Marketing  
Customer Service
- **Vietnam**  
Component (TOSA & BOSA) Manufacturing  
PON Module Manufacturing  
BOSA/Q-OSA & Module Customer Service
- **China: Shenzhen, China**  
Component & Module Supply Chain Management

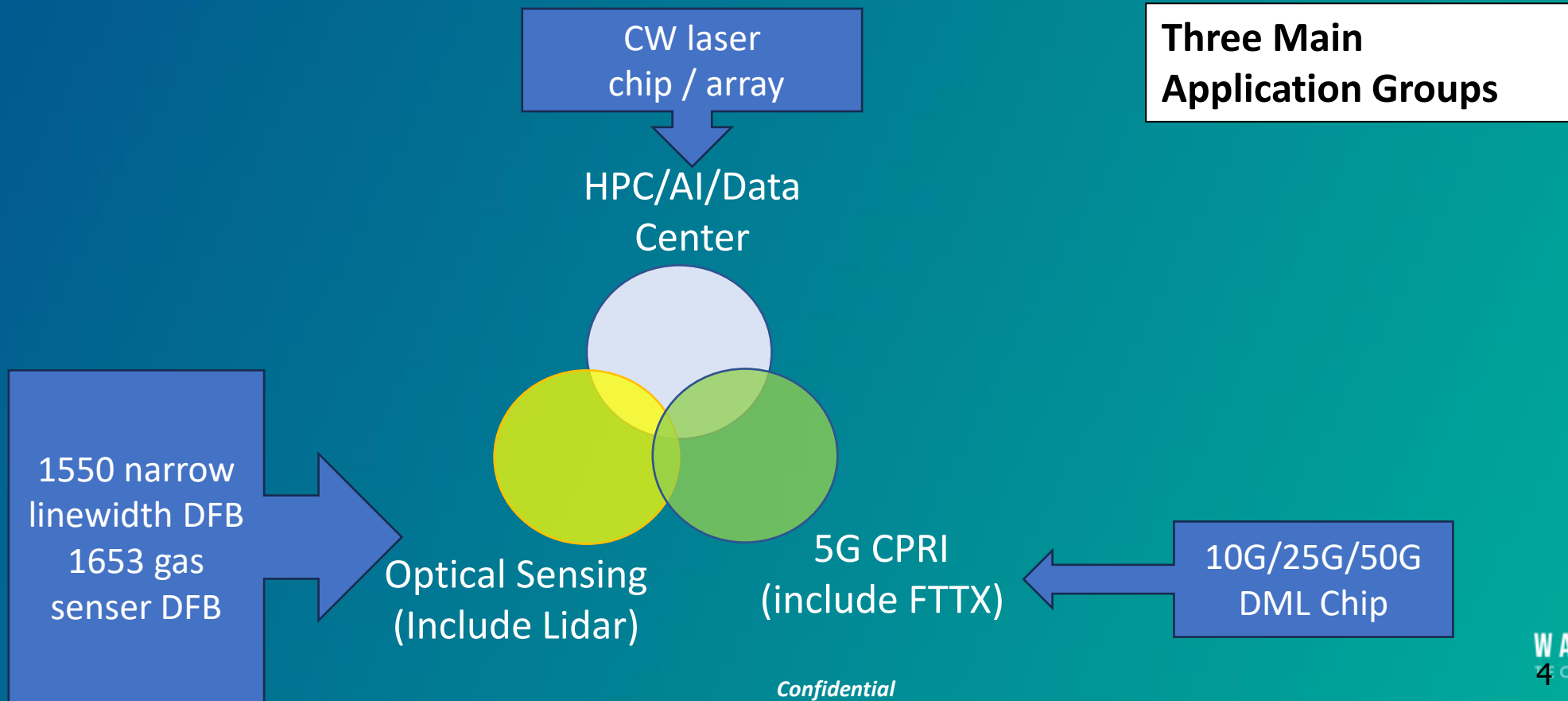
**Lighting the Cloud on Fiber**  
**Paving the Way for 5G Networks, AI, HPC, Datacenter and**  
**Sensing for Self Driving**





# Company Missions

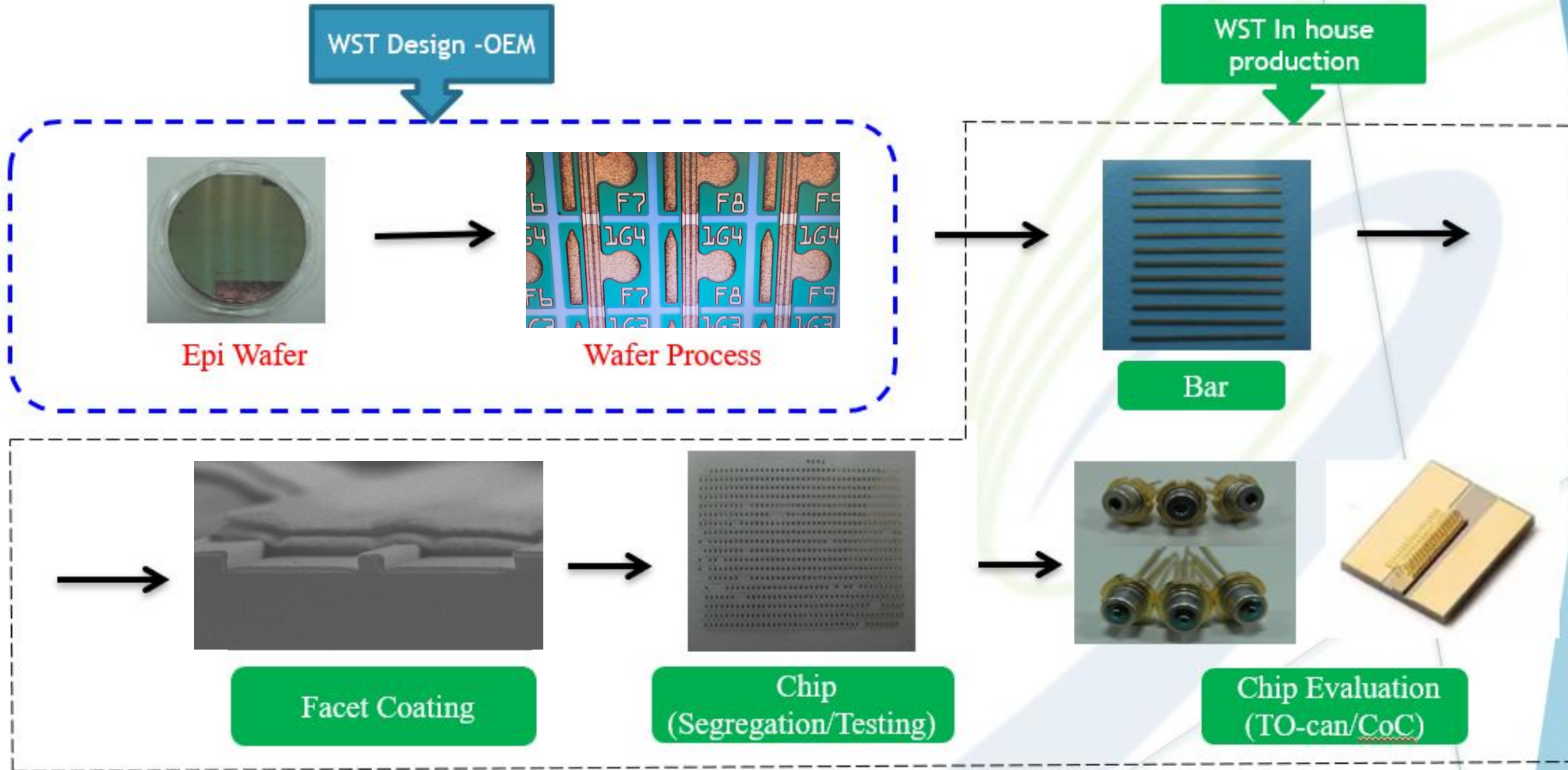
Be a leading suppliers of optical solutions for 5G Networking, HPC/AI, Datacenter as well as Optical Sensing Applications.



Confidential



# DFB LD / CW LD Chip Process Flow



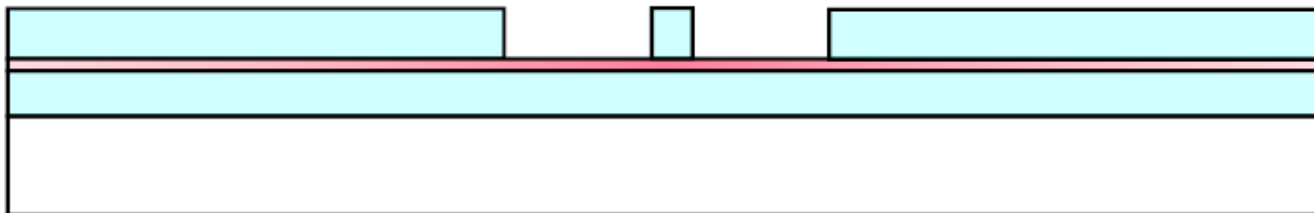
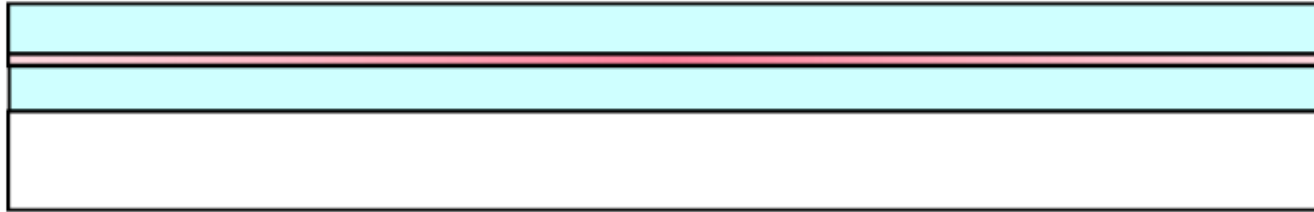


# Chip current position

- ◆ CW laser chip: 70mW CW laser chip compete to Broadcom chip
- ◆ 100mW CW laser chip will be MP 2024
- ◆ 400G DR4 Optical engine & OSFP 800G 2xDR4 LPOTRX sample ready
- ◆ by 2025 Q1
  
- ◆ 10G/25G /50G PON DML chip :
  - 10G PON: The best C/P chip
  - 25G PON : Leading company
  - 50G PON & Data Center: Samples will be ready by end of 2024
  
- ◆ 1550nm narrow linewidth DFB chip: developing
- ◆ 1653nm DFB gas sensor: developing with customer

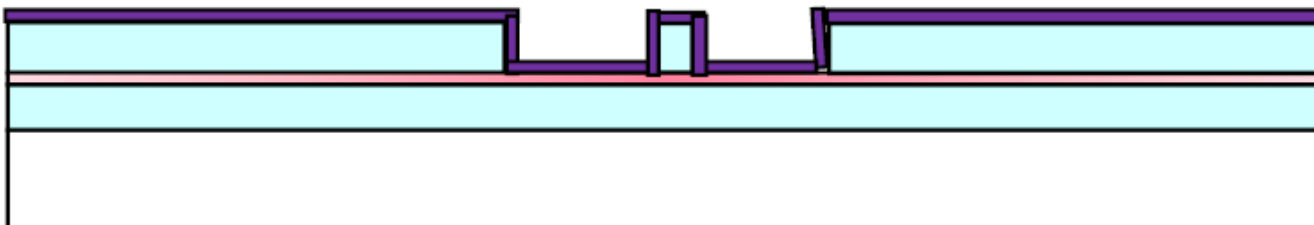


# Wafer process -1/3



## Mask 1: Ridge

Dry+Wet etching  
Ridge width 2.0um  
Etching stop layer at 1.85um

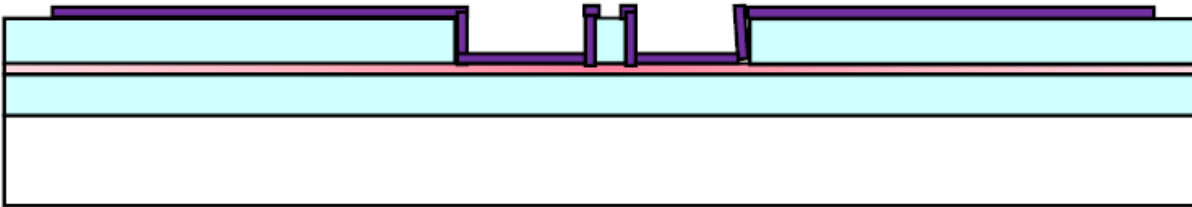


## Passivation film

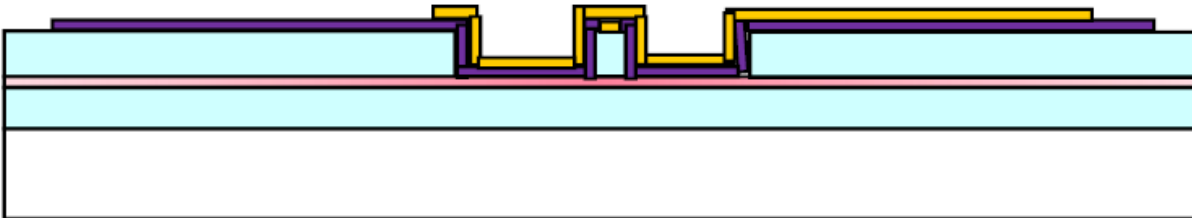
SiNx=0.3um



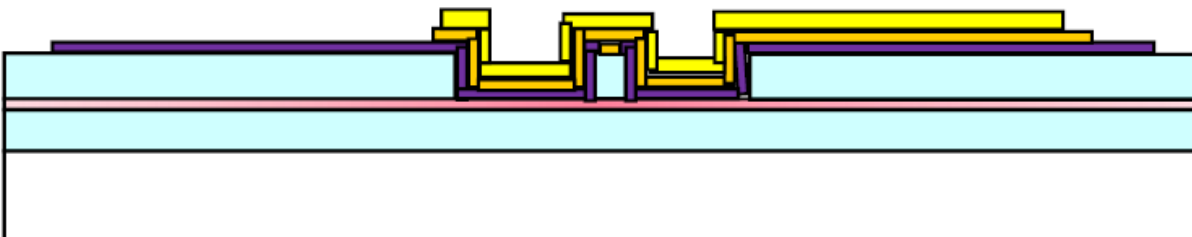
# Wafer process -2/3



**Mask 2:**  
**Open contact**  
Dry+Wet etching



**Mask 3: P-metal**  
Ti / Pt / Au=0.5um  
Anneal 400°C

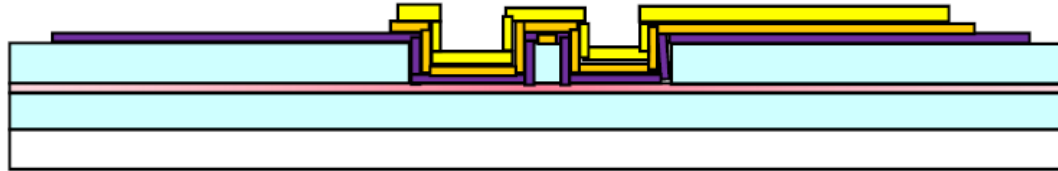


**Mask 4:**  
**Au-plating**  
Au=1um

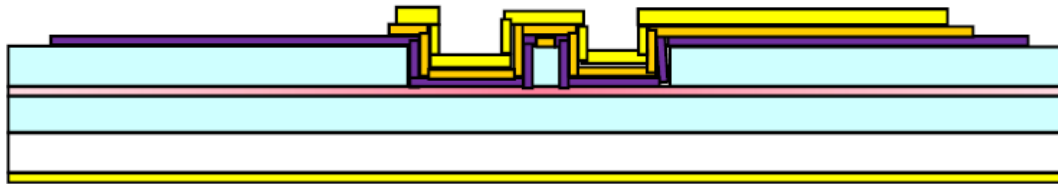




# Wafer process -3/3

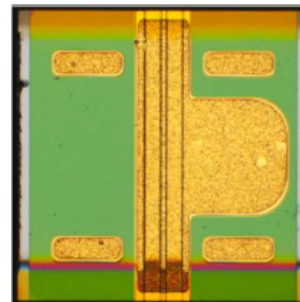
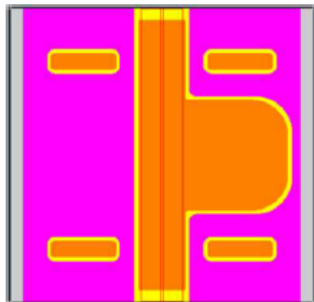


Wafer Lapping  
thickness : 120um+/-10um



N-metal  
AuGeNi/Au=0.4um  
RTA Anneal

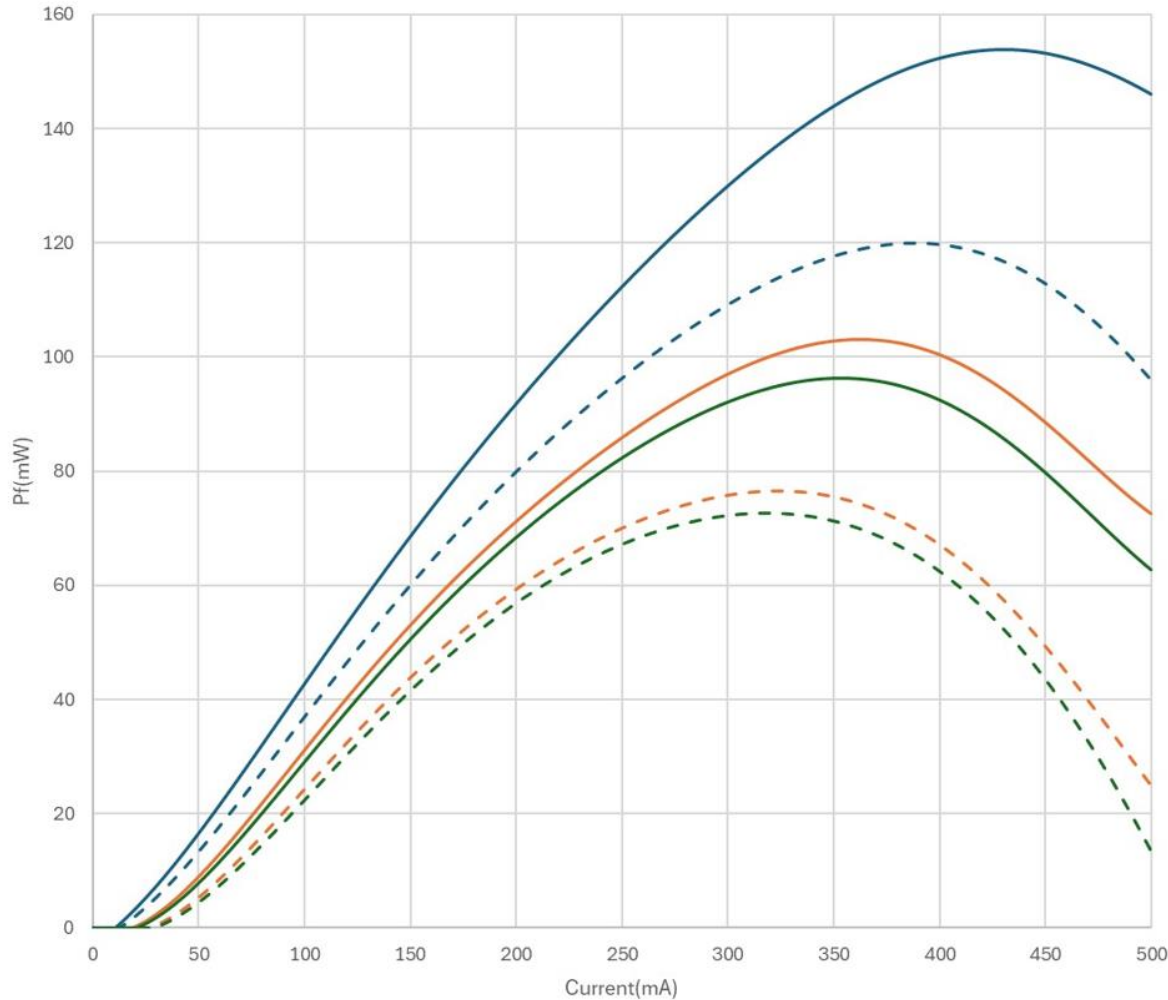
Top View





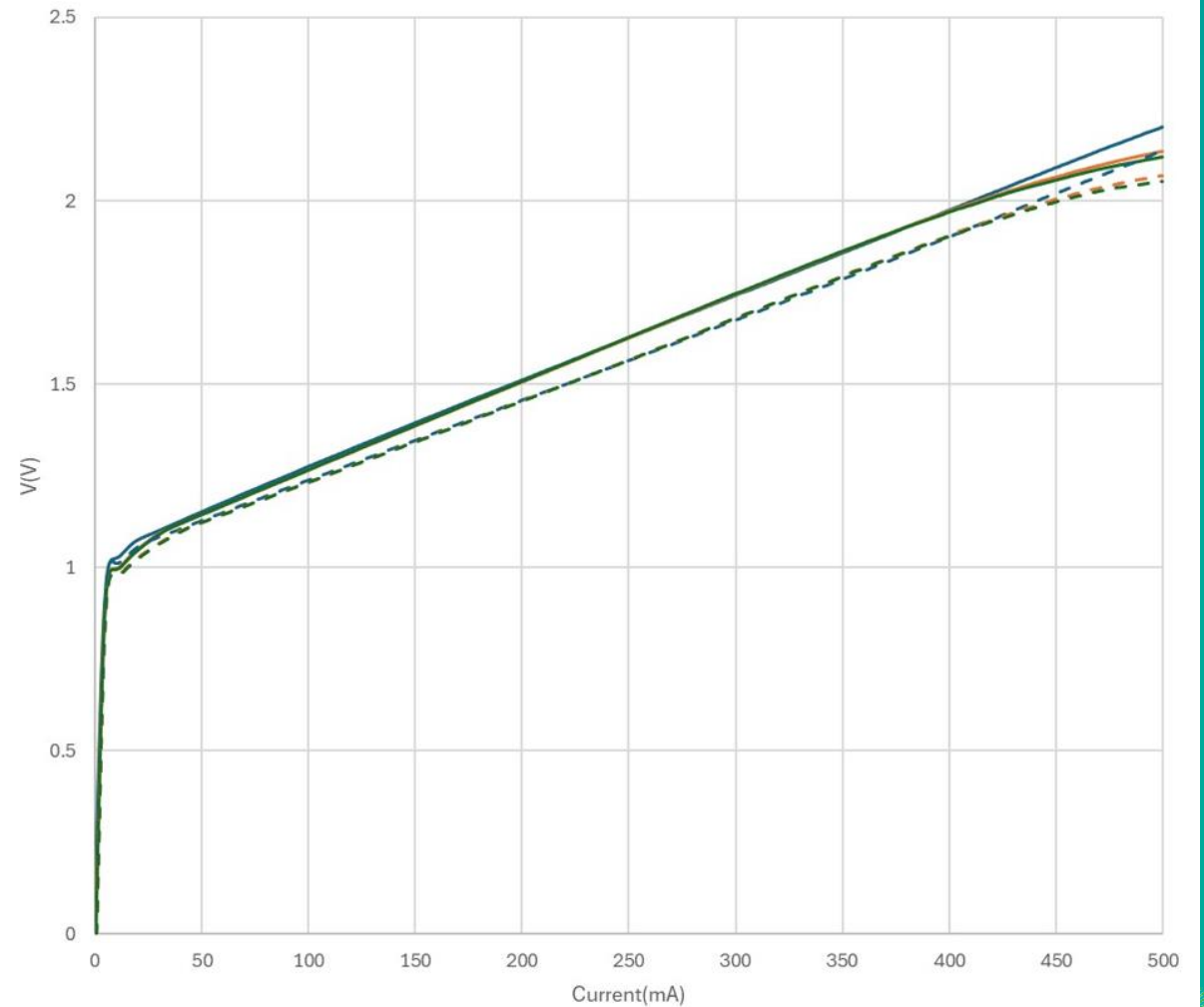
# High Power 1310nm CW DFB Laser LIV Curve (800um CL old -70mW vs new version-100mW)

800um 1310nm CW laser IL curve



— NEW Pf(mW)-25°C — NEW Pf(mW)-70°C — NEW Pf(mW)-75°C  
- - - OLD Pf(mW)-25°C - - - OLD Pf(mW)-70°C - - - OLD Pf(mW)-75°C

800um 1310nm CW laser IV curve



— NEW V(V)-25°C — NEW V(V)-70°C — NEW V(V)-75°C  
- - - OLD V(V)-25°C - - - OLD V(V)-70°C - - - OLD V(V)-75°C

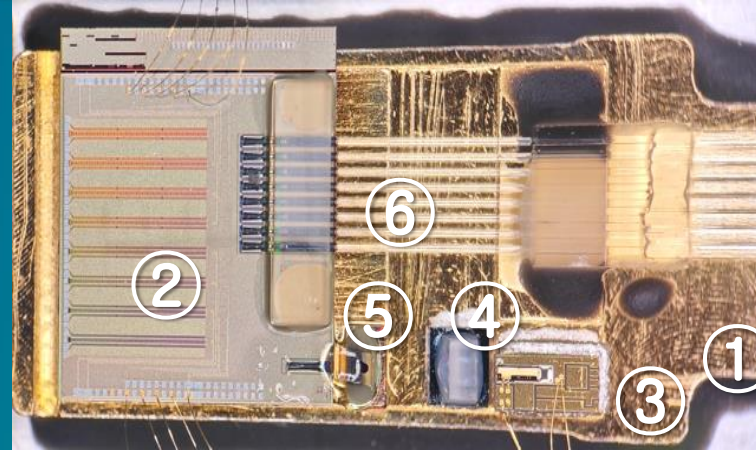


# CW LD Application (Transceiver)

(Chip → Optical Engine → LPO Transceiver)

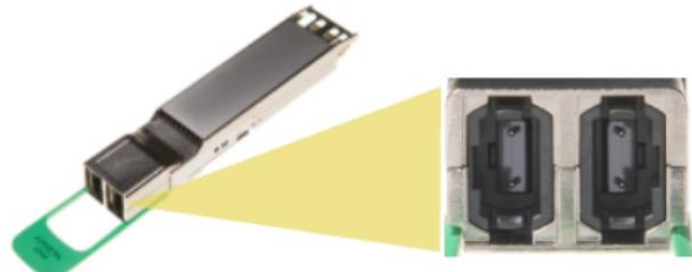


DFB Chip



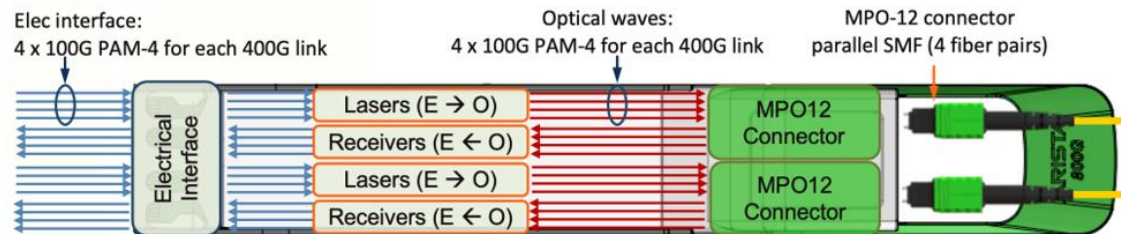
Optical Engine

①	Metal Base
②	PIC
③	CoC
④	ASP Lens
⑤	Isolator
⑥	Fiber Array



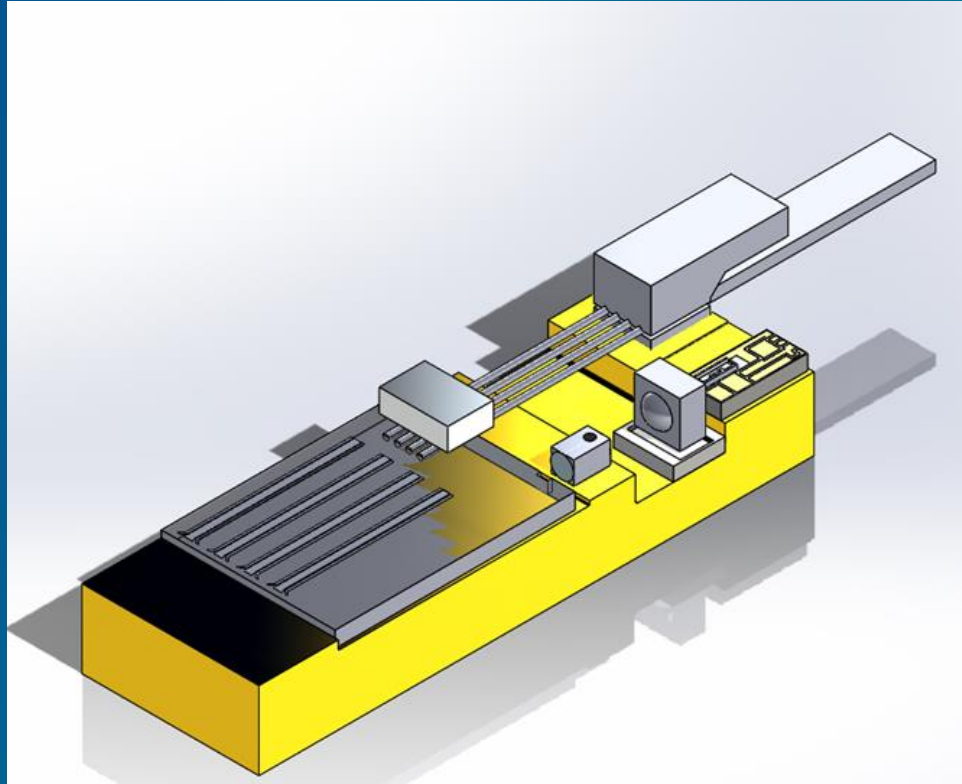
LPO Transceiver

Data path block diagram of 800G-2XDR4 / 2PLR4 modules

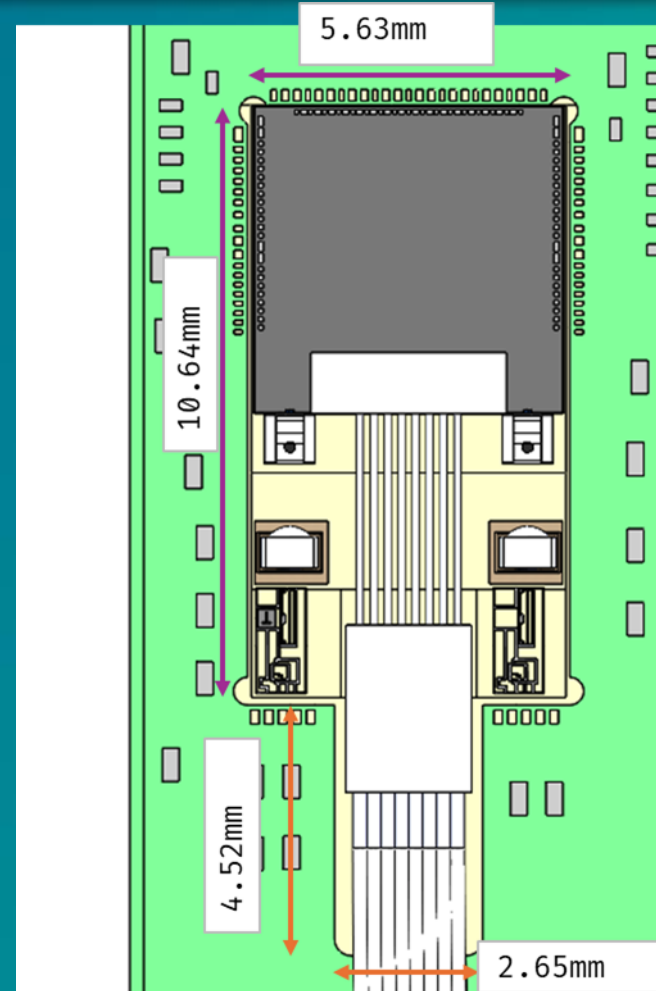




# 400G DR4 / 800G (2\*DR4) Optical Engine



400G O/E

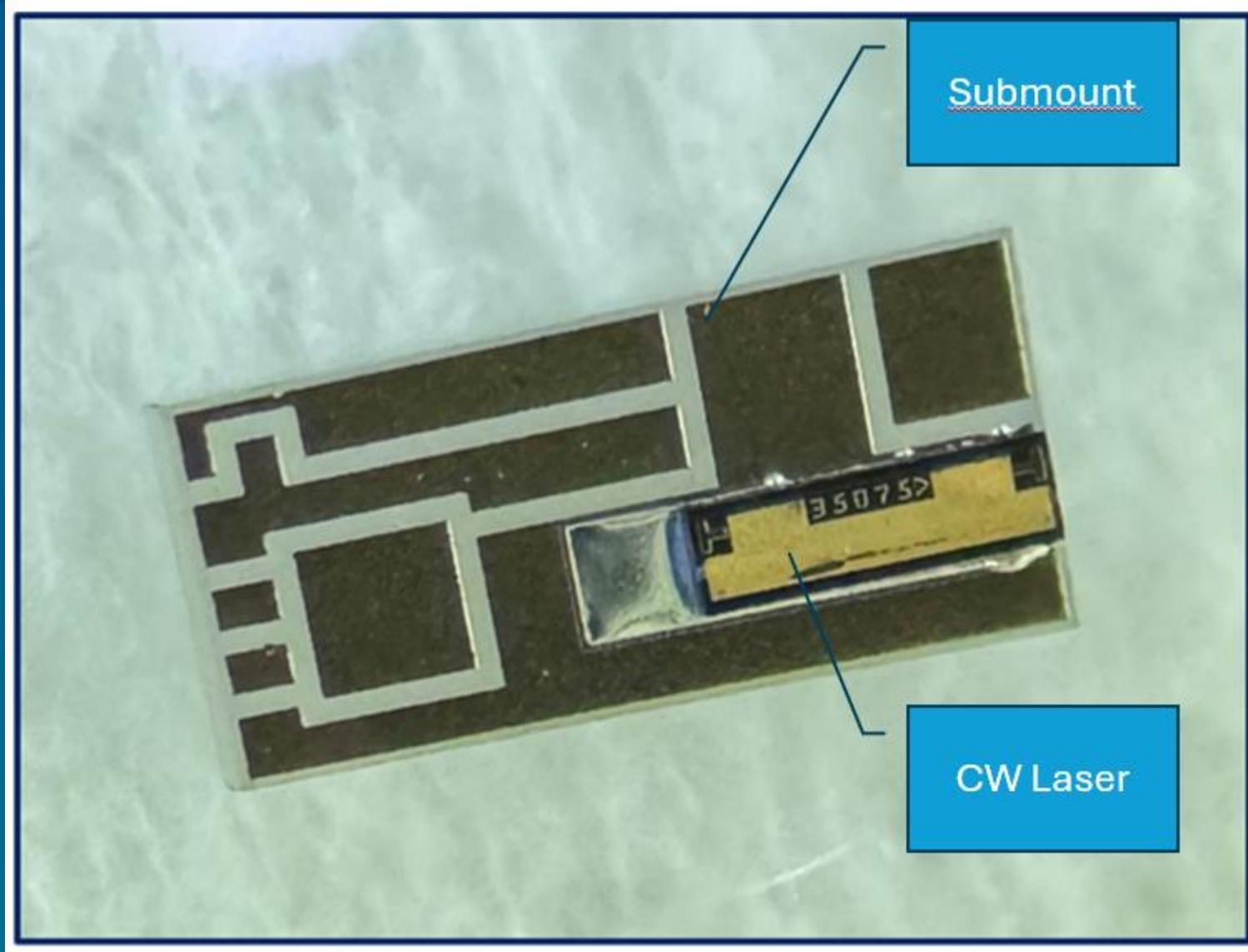


800G O/E



# *Optical Engine process 1/7*

## *CW Laser CoC*

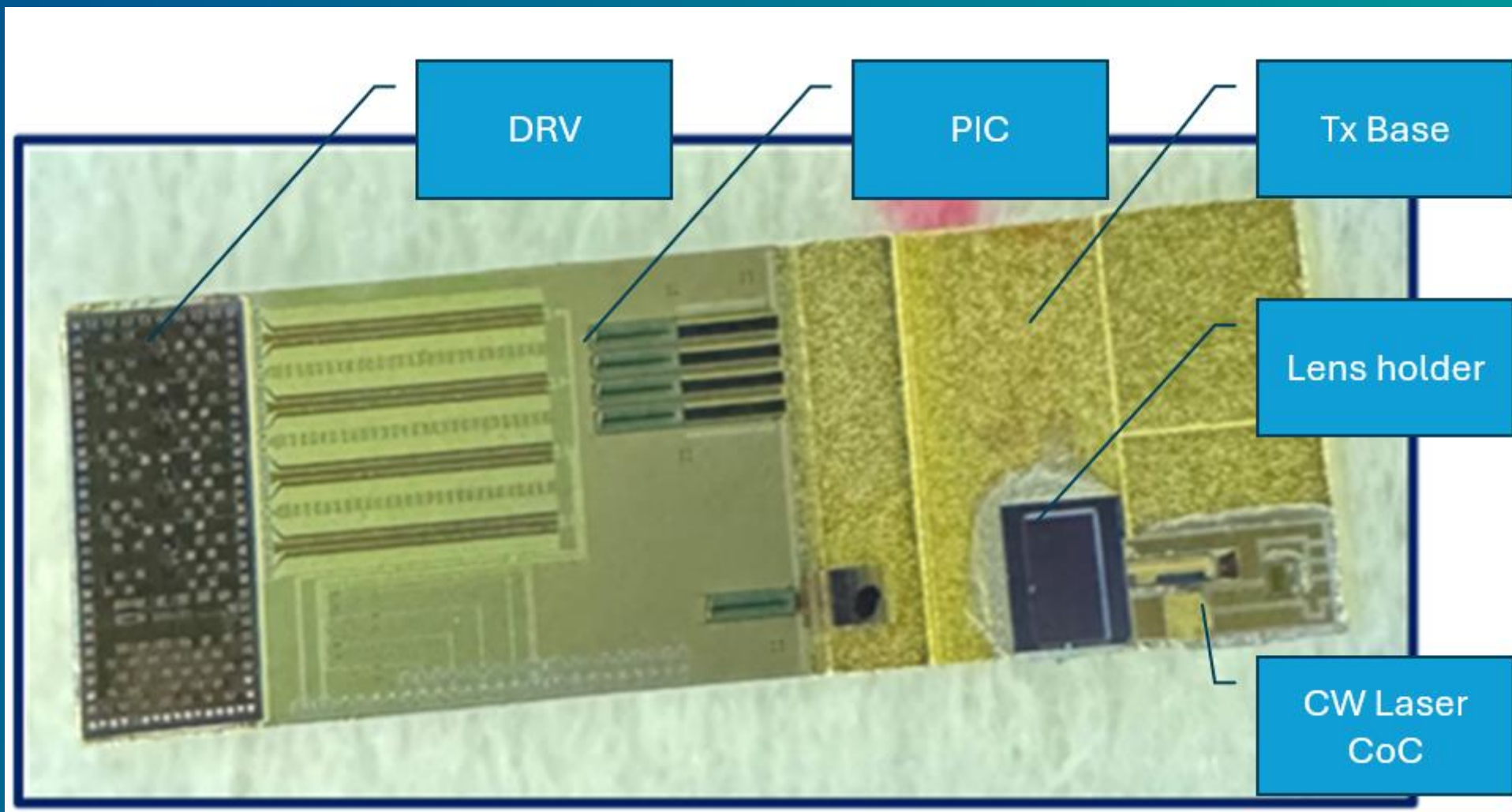






# *Optical Engine process 2/7*

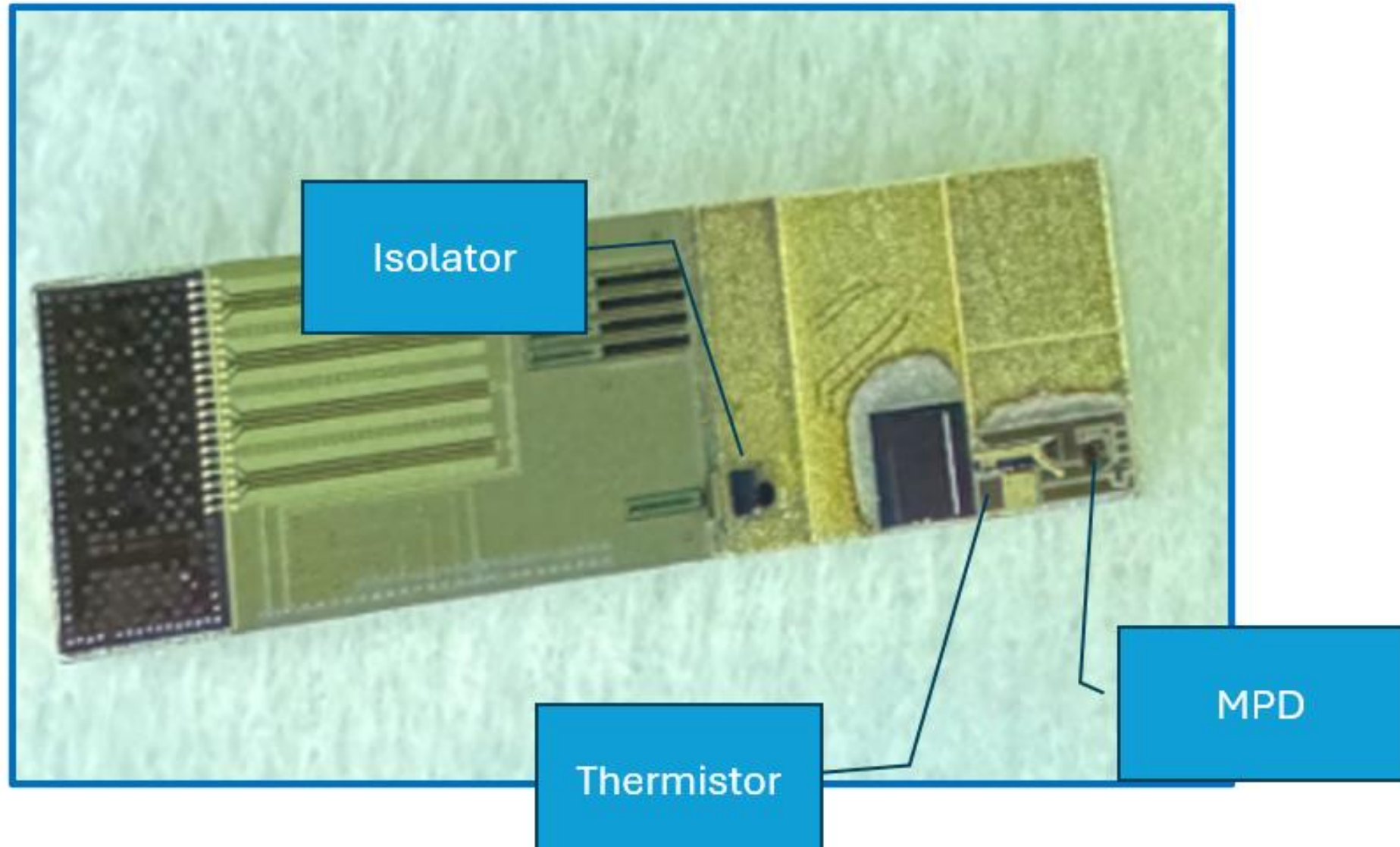
## *Put PIC/Lens CoC/Lens holder into TX Base*





# *Optical Engine process 3/7*

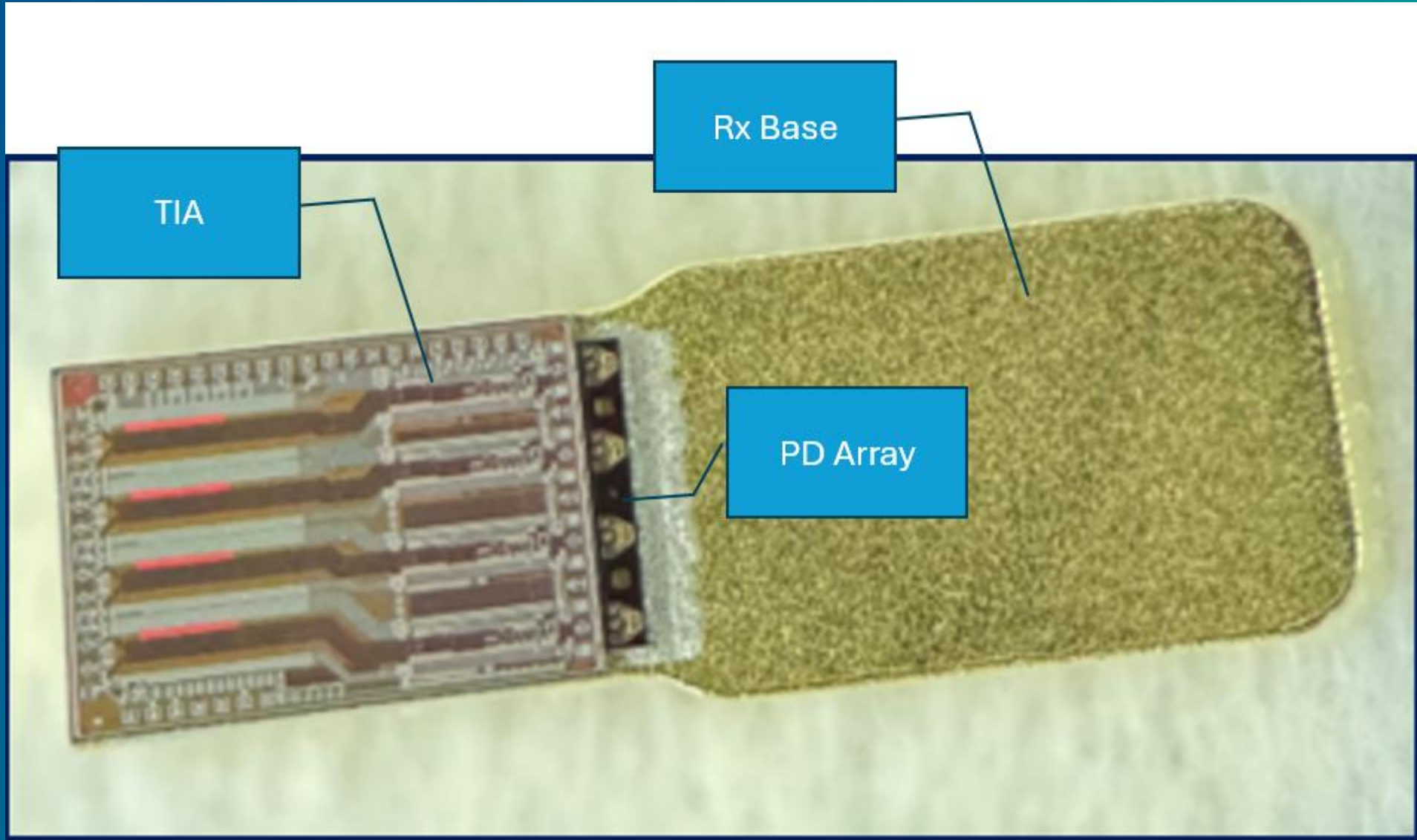
## *Put Isolator / Thermistor / MPD into TX Base*





# *Optical Engine process 4/7*

## *Put TIA/ PD Array into RX Base*

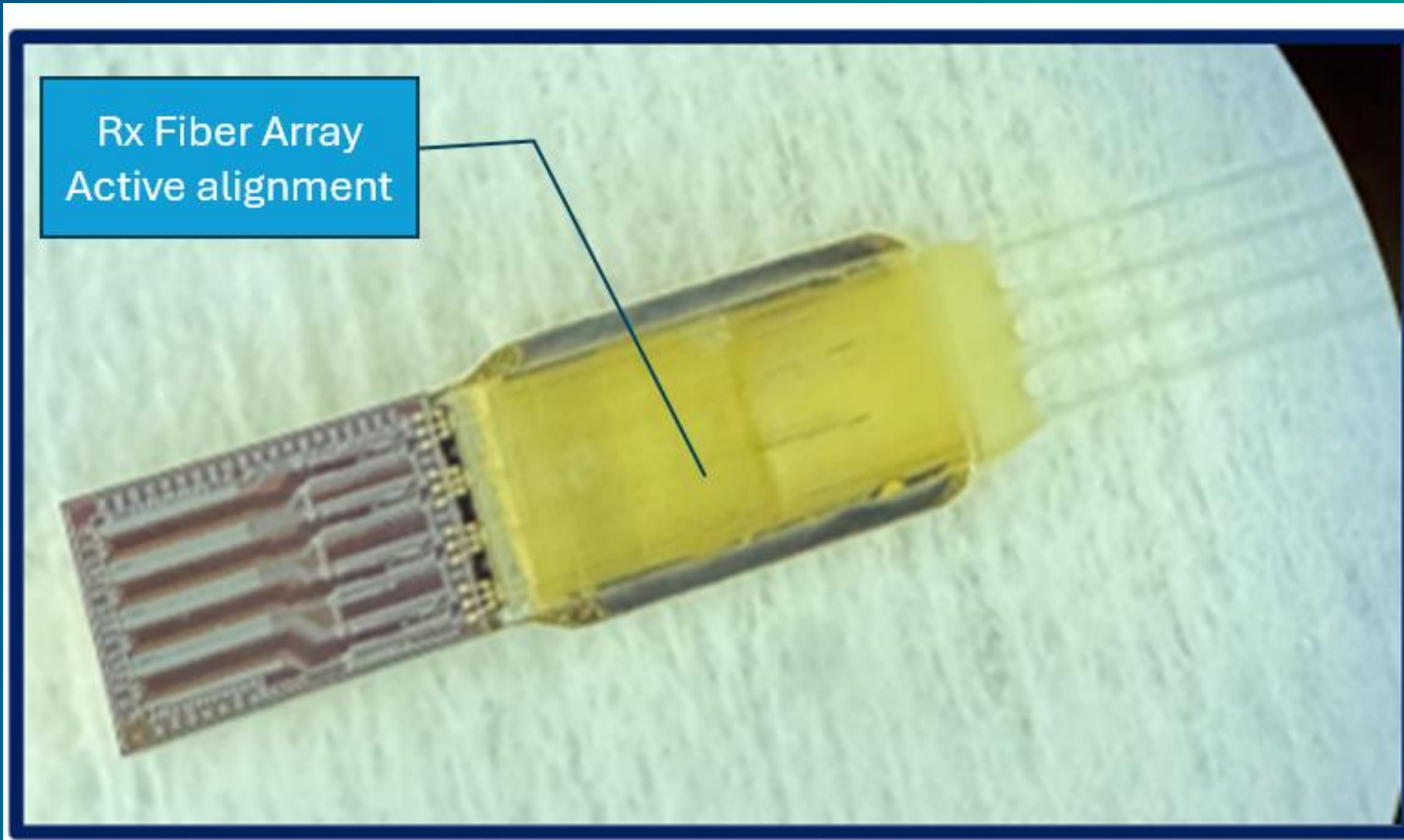






# *Optical Engine process 5/7*

## *RX Fiber Array Active Alignment(45D)*





# *Optical Engine process 6/7*

## *TX Fiber Array Passive Alignment*

### *(Fiber into V Groove)*

Tx Fiber Array  
W/ MT connector







# *Optical Engine process 7/7*

## *TX Lens Active Alignment*

